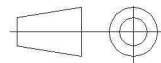
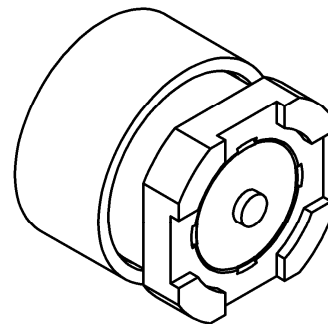
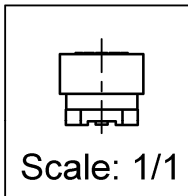
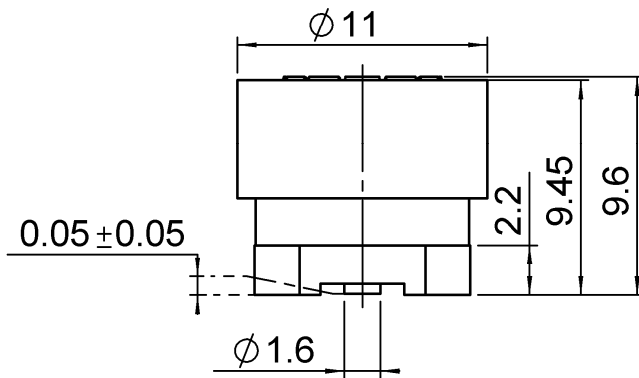
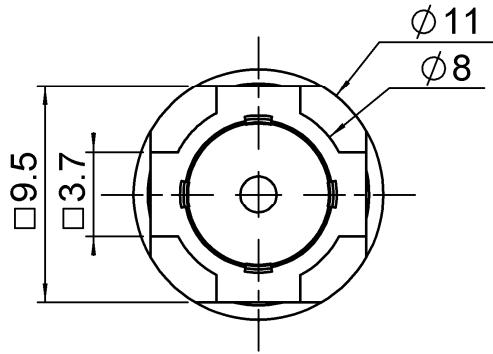


STRAIGHT MALE RECEPTACLE FOR SMT

R328.424.012

SNAP TYPE

Series : **BMR-SPRING**



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (µm)
BODY	BRASS	NPGR ; BBR
CENTER CONTACT	BRASS	NPGR
OUTER CONTACT		
INSULATOR	PEEK	
GASKET		
OTHERS PARTS	BERYLLIUM COPPER	BBR
.	.	.
.	.	.

Issue : 1042 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



STRAIGHT MALE RECEPTACLE FOR SMT

R328.424.012

SNAP TYPE

Series : **BMR-SPRING**

PACKAGING

SPECIFICATION

Standard	Unit	Other
100	'W' option	Contact us

ELECTRICAL CHARACTERISTICS

ENVIRONMENTAL

Impedance		50 Ω
Frequency		0-8 GHz
VSWR	1.2* +	0,0000 x F(GHz) Maxi
Insertion loss		0.1** √F(GHz) dB Maxi
RF leakage	- (TBT - F(GHz)) dB Maxi
Voltage rating		500 Veff Maxi
Dielectric withstanding voltage		1000 Veff mini
Insulation resistance		5000 MΩ mini

Operating temperature	-40/+120 ° C
Hermetic seal	NA Atm.cm3/s
Panel leakage	NA

OTHER CHARACTERISTICS

Assembly instruction **NA**

Others :

*up to 3GHz , 0-6GHz:1.25Max,0-8GHz:1.35

*Measured by one bullet+two connectors

*,**Coaxial Transmission Line Only

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating end	18	N mini
Axial force – Opposite end	18	N mini
Torque	NA	N.cm mini
Recommended torque		
Mating	NA	N.cm
Panel nut	NA	N.cm
Mating life	100	Cycles mini
Weight	4,3600	g

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STRAIGHT MALE RECEPTACLE FOR SMT

R328.424.012

SNAP TYPE

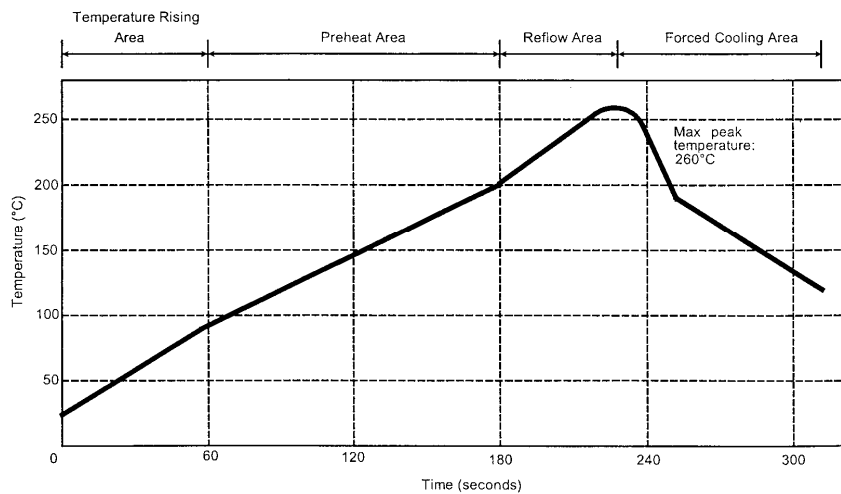
Series : **BMR-SPRING**

SOLDER PROCEDURE

1. Deposit solder paste ‘SnAg4Cu0.5’ on mounting zone by screen printing application. We recommend a low residue flux.
We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of ‘pick and place’ type. A video camera is recommended for positioning of the component . Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
4. The cleaning of printed circuit boards is not obliged .

Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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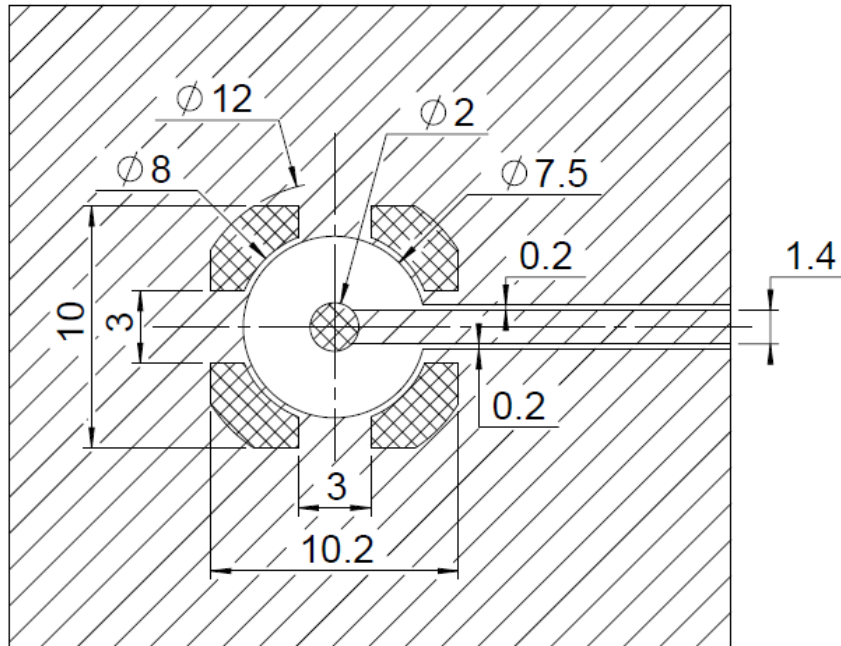
STRAIGHT MALE RECEPTACLE FOR SMT


R328.424.012


SNAP TYPE

Series : **BMR-SPRING**

PCB Layout

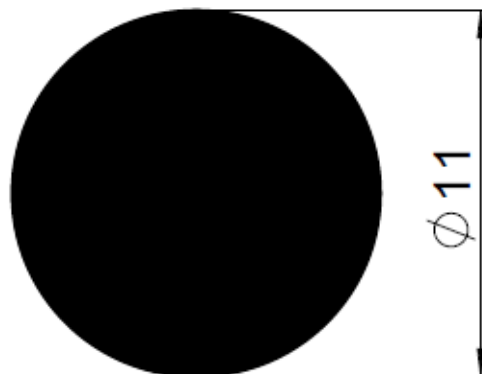


 Land for solder paste

 Pattern

COPLANAR LINE : Pattern and signal are on the same side. Thickness of PCB = 1.5 mm(double sides). The material of PCB is RO4350. The solder resist should be printed except for the land pattern on the PCB.

Shadow of receptacle for video camera



Issue : 1042 A

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